

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
Name		Execution Date
Tsann Lin		05/28/2008
RECEIVING PARTY DATA		
Name:	Hitachi Global Storage Technologies Netherlands B.V.	
Street Address:	Locatellikade 1	
Internal Address:	Parnassustoren	
City:	1076 AZ Amsterdam	
State/Country:	NETHERLANDS	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	12129120	
CORRESPONDENCE DATA		
Fax Number:	(303)786-7691	
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>		
Phone:	303-786-7687	
Email:	mnguyen@dbflaw.com	
Correspondent Name:	Brett Bornsen	
Address Line 1:	1526 SPRUCE STREET	
Address Line 2:	SUITE 302	
Address Line 4:	BOULDER, COLORADO 80302	
ATTORNEY DOCKET NUMBER:	HSJ920080044US1	
NAME OF SUBMITTER:	Brett Bornsen	
Total Attachments: 1 source=34010-077Assignment#page1.tif		

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PATENT
REEL: 021015 FRAME: 0903

ASSIGNMENT FOR PATENT APPLICATION

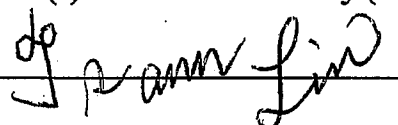
Whereas, I/we the undersigned inventor(s) have invented certain improvements as set forth in the patent application entitled:

A CURRENT-PERPENDICULAR-TO-PLANE (CPP) READ SENSOR WITH SMOOTHENED MULTIPLE REFERENCE LAYERS

Whereas, **Hitachi Global Storage Technologies Netherlands B.V.**, having a place of business at Locatellikade 1, Parnassustoren, 1076 AZ Amsterdam, The Netherlands (hereinafter referred to as "HITACHI"), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to HITACHI, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to HITACHI, its successors and assigns; and we hereby agree that HITACHI may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by HITACHI.

Signed on the date(s) indicated beside my (our) signature(s).

1) Signature: 
Tsann Lin

Date: 5/28/2008